

General Description

- Trench Power MV MOSFET technology
- Low $R_{DS(ON)}$
- Low Gate Charge
- Optimized for fast-switching applications

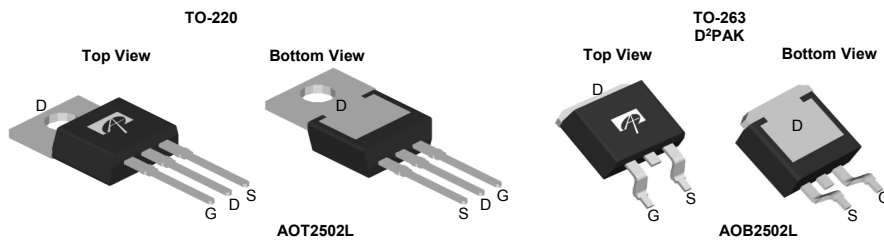
Applications

- Synchronous Rectification in DC/DC and AC/DC Converters
- Industrial and Motor Drive applications

Product Summary

V_{DS}	150V
I_D (at $V_{GS}=10V$)	106A
$R_{DS(ON)}$ (at $V_{GS}=10V$)	< 11m Ω (10.7m Ω^*)

100% UIS Tested
 100% Rg Tested



Orderable Part Number	Package Type	Form	Minimum Order Quantity
AOT2502L	TO-220	Tube	1000
AOB2502L	TO-263	Tape & Reel	800

Absolute Maximum Ratings $T_A=25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Maximum	Units
Drain-Source Voltage	V_{DS}	150	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current	I_D	$T_C=25^\circ\text{C}$	106
		$T_C=100^\circ\text{C}$	67
Pulsed Drain Current ^C	I_{DM}	250	A
Continuous Drain Current	I_{DSM}	$T_A=25^\circ\text{C}$	18.5
		$T_A=70^\circ\text{C}$	14.5
Avalanche Current ^C	I_{AS}	40	A
Avalanche energy $L=0.3\text{mH}$ ^C	E_{AS}	240	mJ
V_{DS} Spike	V_{SPIKE}	180	V
Power Dissipation ^B	P_D	$T_C=25^\circ\text{C}$	277
		$T_C=100^\circ\text{C}$	111
Power Dissipation ^A	P_{DSM}	$T_A=25^\circ\text{C}$	8.3
		$T_A=70^\circ\text{C}$	5.3
Junction and Storage Temperature Range	T_J, T_{STG}	-55 to 150	$^\circ\text{C}$

Thermal Characteristics

Parameter	Symbol	Typ	Max	Units
Maximum Junction-to-Ambient ^A	$R_{\theta JA}$	12	15	$^\circ\text{C/W}$
Maximum Junction-to-Ambient ^{A,D}		Steady-State	50	60
Maximum Junction-to-Case	$R_{\theta JC}$	0.35	0.45	$^\circ\text{C/W}$

* Surface mount package TO-263

Electrical Characteristics (T_J=25°C unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units	
STATIC PARAMETERS							
BV _{DSS}	Drain-Source Breakdown Voltage	I _D =250μA, V _{GS} =0V	150			V	
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =150V, V _{GS} =0V T _J =55°C			1 5	μA	
I _{GSS}	Gate-Body leakage current	V _{DS} =0V, V _{GS} =±20V			±100	nA	
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250μA	3.5	4.3	5.1	V	
R _{DS(on)}	Static Drain-Source On-Resistance	V _{GS} =10V, I _D =20A TO-220 T _J =125°C		9.2 17.8	11 21.5	mΩ	
		V _{GS} =10V, I _D =20A TO-263		8.9	10.7	mΩ	
g _{FS}	Forward Transconductance	V _{DS} =5V, I _D =20A		50		S	
V _{SD}	Diode Forward Voltage	I _S =1A, V _{GS} =0V		0.7	1	V	
I _S	Maximum Body-Diode Continuous Current				106	A	
DYNAMIC PARAMETERS							
C _{iss}	Input Capacitance	V _{GS} =0V, V _{DS} =75V, f=1MHz		3010		pF	
C _{oss}	Output Capacitance				345		pF
C _{riss}	Reverse Transfer Capacitance				14		pF
R _g	Gate resistance	f=1MHz	1	2	3	Ω	
SWITCHING PARAMETERS							
Q _{g(10V)}	Total Gate Charge	V _{GS} =10V, V _{DS} =75V, I _D =20A		43	60	nC	
Q _{gs}	Gate Source Charge				18		nC
Q _{gd}	Gate Drain Charge				10		nC
t _{D(on)}	Turn-On DelayTime	V _{GS} =10V, V _{DS} =75V, R _L =3.75Ω, R _{GEN} =3Ω		19		ns	
t _r	Turn-On Rise Time				24		ns
t _{D(off)}	Turn-Off DelayTime				30		ns
t _f	Turn-Off Fall Time				8.5		ns
t _{rr}	Body Diode Reverse Recovery Time	I _F =20A, dI/dt=500A/μs		75		ns	
Q _{rr}	Body Diode Reverse Recovery Charge	I _F =20A, dI/dt=500A/μs		880		nC	

A. The value of R_{θJA} is measured with the device mounted on 1 in² FR-4 board with 2oz. Copper, in a still air environment with T_A =25° C. The Power dissipation P_{D(SM)} is based on R_{θJA} ≤ 10s and the maximum allowed junction temperature of 150° C. The value in any given application depends on the user's specific board design, and the maximum temperature of 150° C may be used if the PCB allows it.

B. The power dissipation P_D is based on T_{J(MAX)}=150° C, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heatsinking is used.

C. Single pulse width limited by junction temperature T_{J(MAX)}=150° C.

D. The R_{θJA} is the sum of the thermal impedance from junction to case R_{θJC} and case to ambient.

E. The static characteristics in Figures 1 to 6 are obtained using <300μs pulses, duty cycle 0.5% max.

F. These curves are based on the junction-to-case thermal impedance which is measured with the device mounted to a large heatsink, assuming a maximum junction temperature of T_{J(MAX)}=150° C. The SOA curve provides a single pulse rating.

G. The maximum current rating is package limited.

H. These tests are performed with the device mounted on 1 in² FR-4 board with 2oz. Copper, in a still air environment with T_A=25° C.

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TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

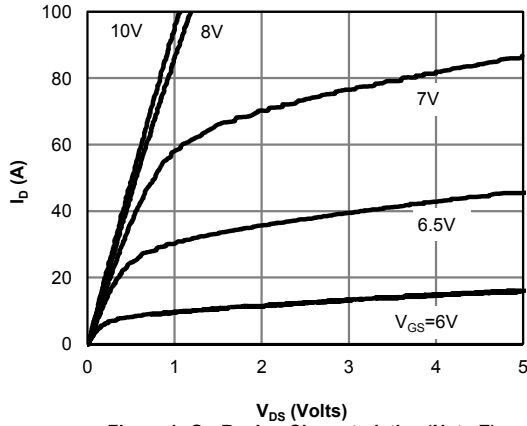


Figure 1: On-Region Characteristics (Note E)

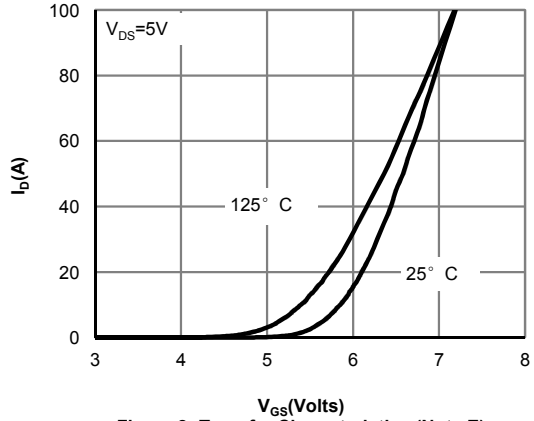


Figure 2: Transfer Characteristics (Note E)

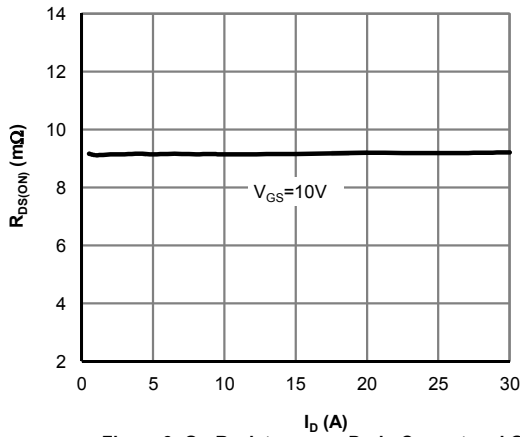


Figure 3: On-Resistance vs. Drain Current and Gate Voltage (Note E)

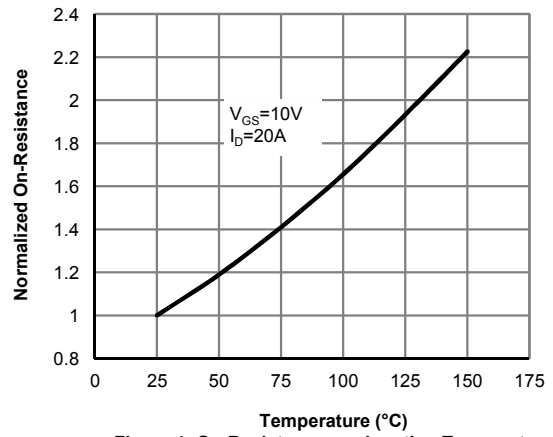


Figure 4: On-Resistance vs. Junction Temperature (Note E)

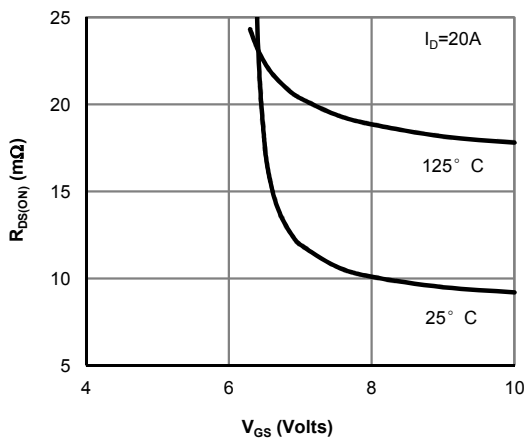


Figure 5: On-Resistance vs. Gate-Source Voltage (Note E)

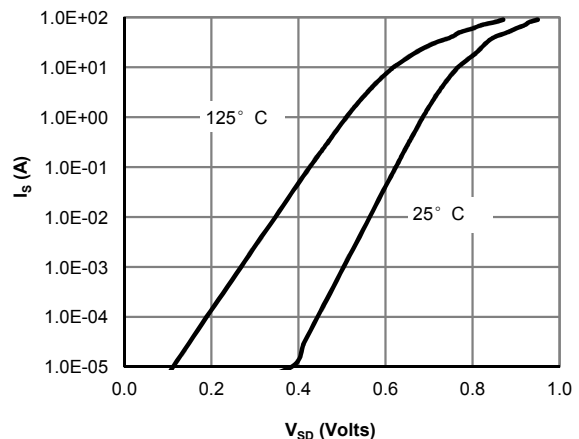


Figure 6: Body-Diode Characteristics (Note E)

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

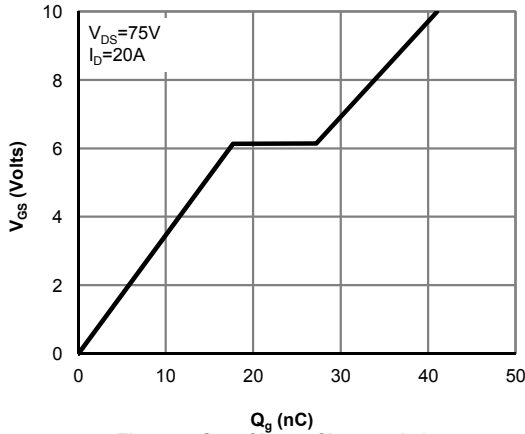


Figure 7: Gate-Charge Characteristics

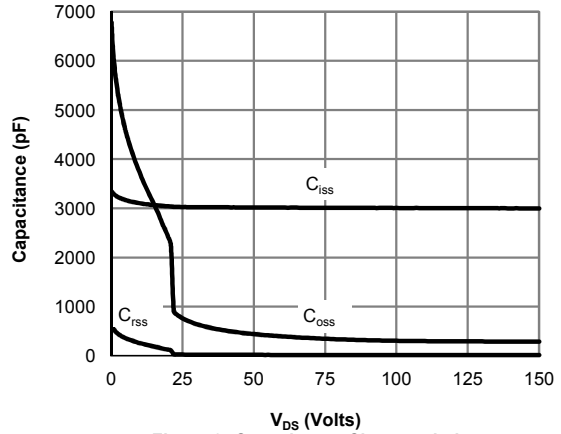


Figure 8: Capacitance Characteristics

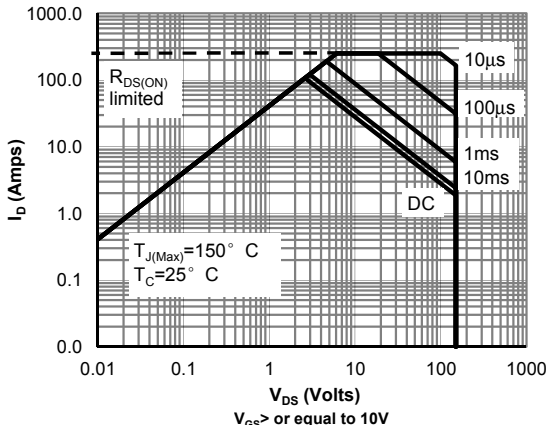


Figure 9: Maximum Forward Biased Safe Operating Area (Note F)

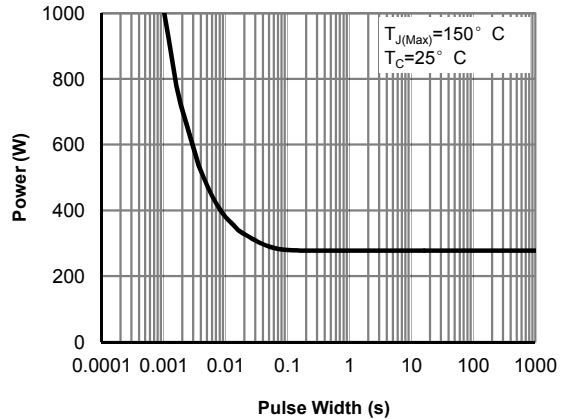


Figure 10: Single Pulse Power Rating Junction-to-Case (Note F)

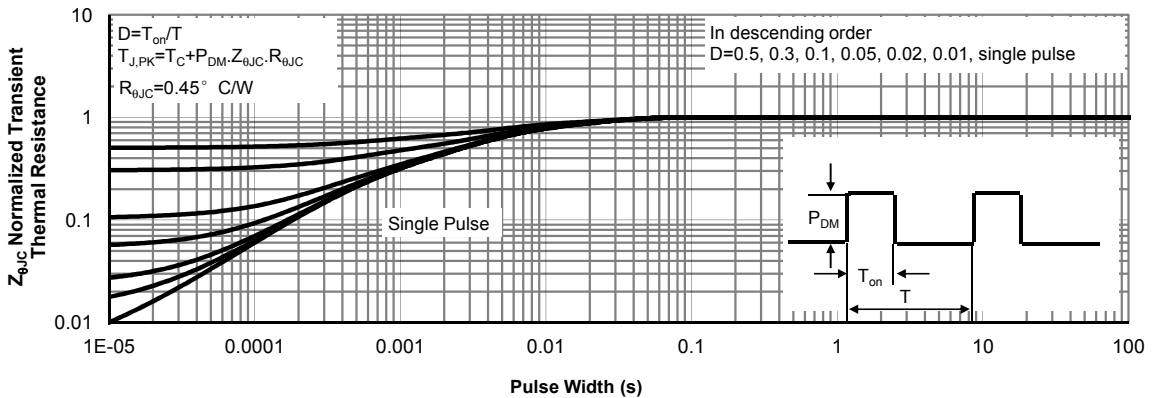


Figure 11: Normalized Maximum Transient Thermal Impedance (Note F)

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

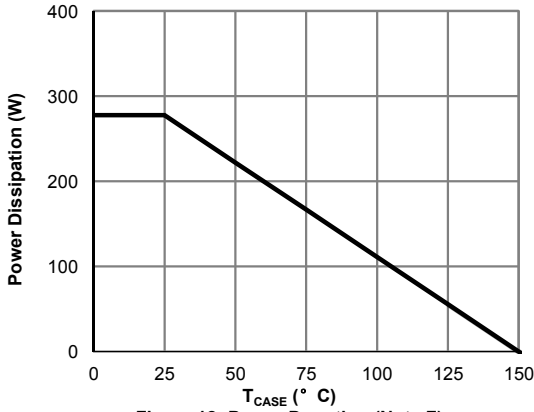


Figure 12: Power De-rating (Note F)

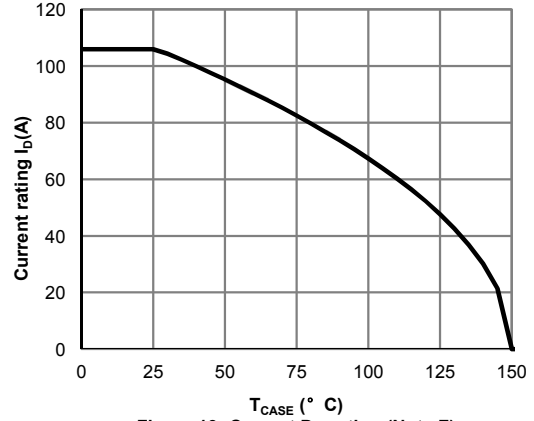


Figure 13: Current De-rating (Note F)

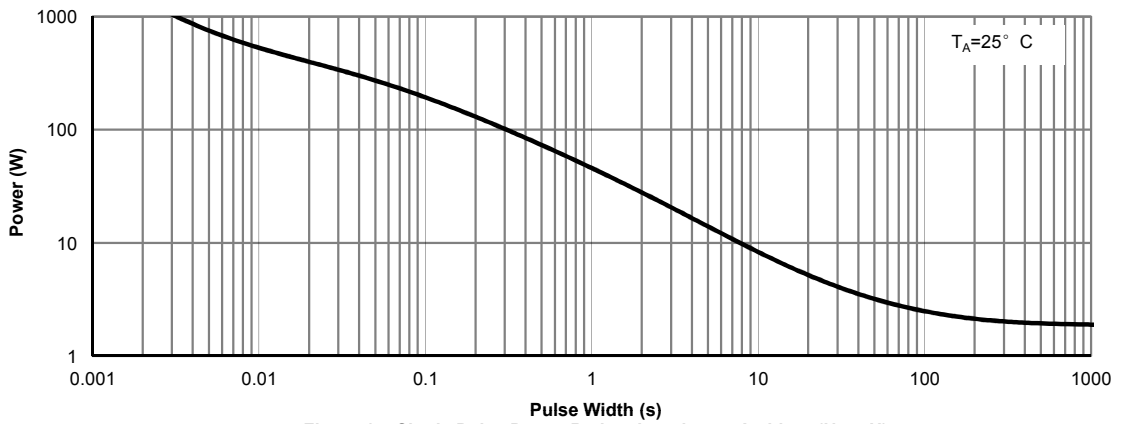


Figure 14: Single Pulse Power Rating Junction-to-Ambient (Note H)

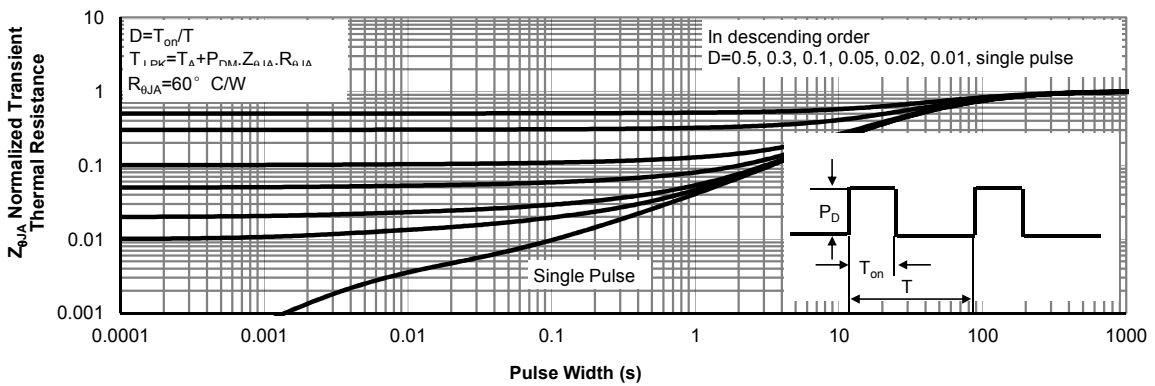
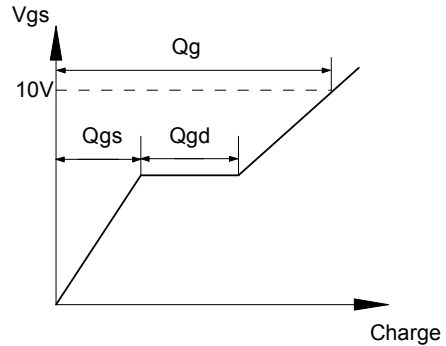
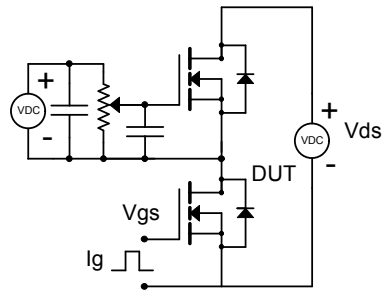
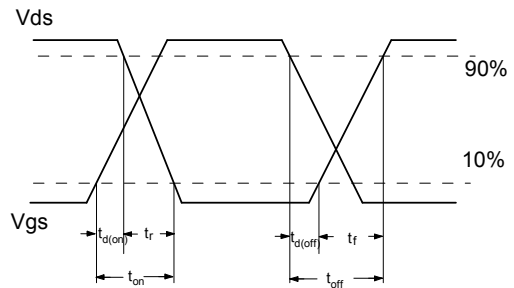
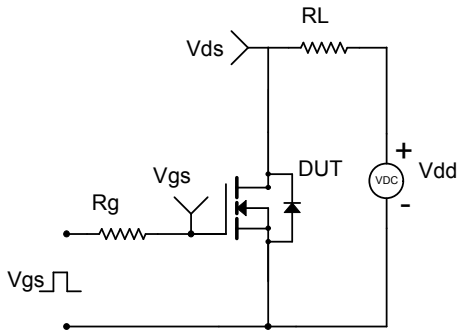


Figure 15: Normalized Maximum Transient Thermal Impedance (Note H)

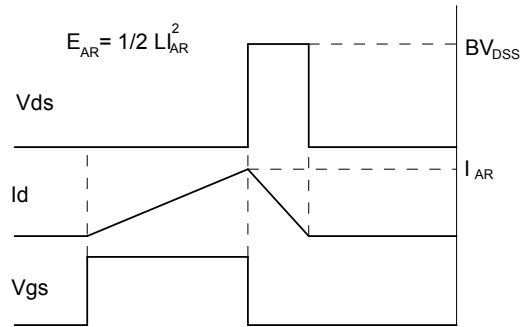
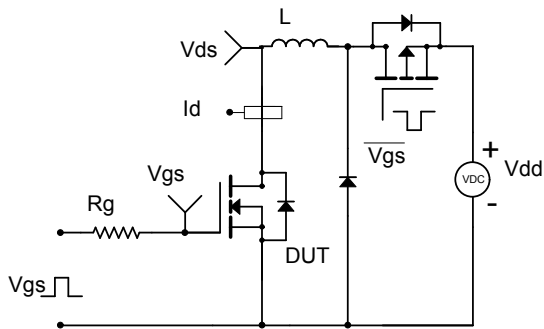
Gate Charge Test Circuit & Waveform



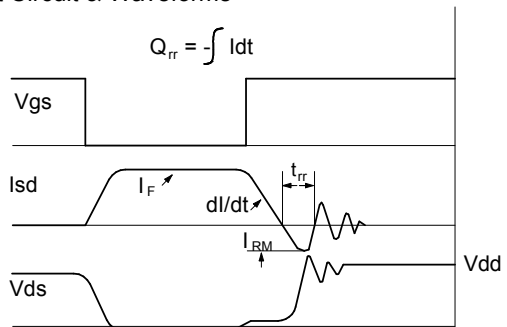
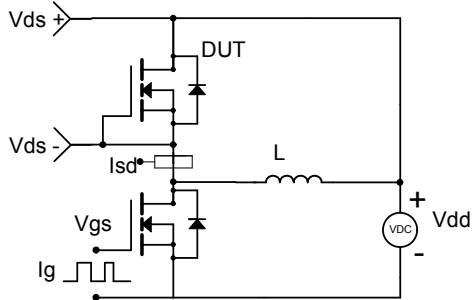
Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms



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